RC Connect-R™

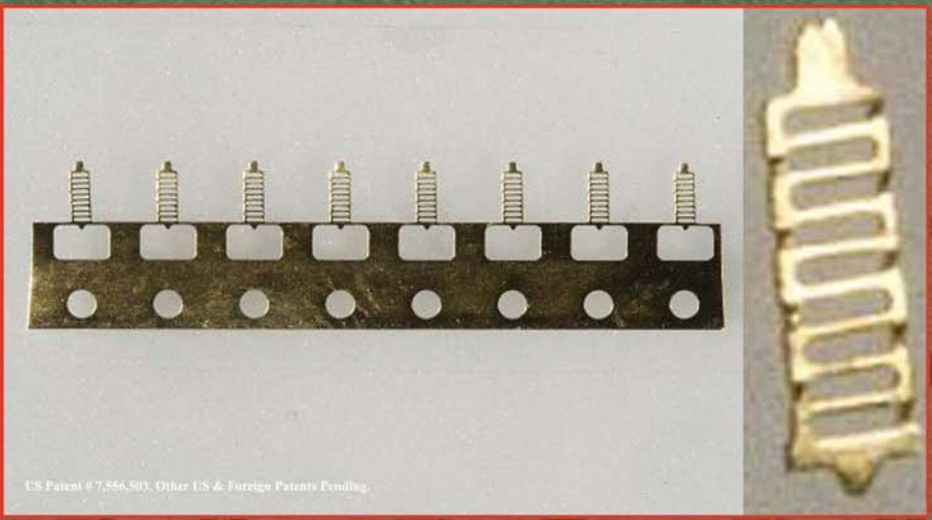
Cost-Effective High-Performance Stamped Contact Technology for Area Array Applications

Highly Consistent Compression Mount Connectors Down to .6mm Pitch

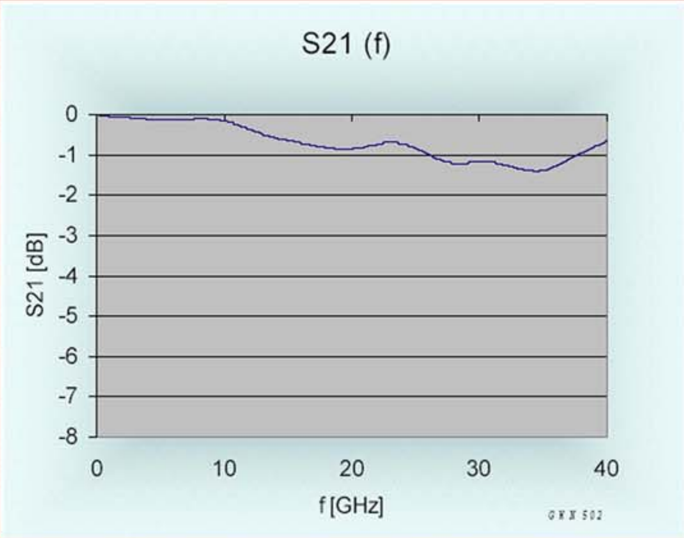
Density & Scalability
Down to .6mm Pitch in Area Array
As Short as 2.2mm Mated Height
Up to 2K+ Nodes Per Connector

Bandwidth & Electrical Performance
As High as 25 GHz at -1dB
As Low as .82 nH Self-Inductance

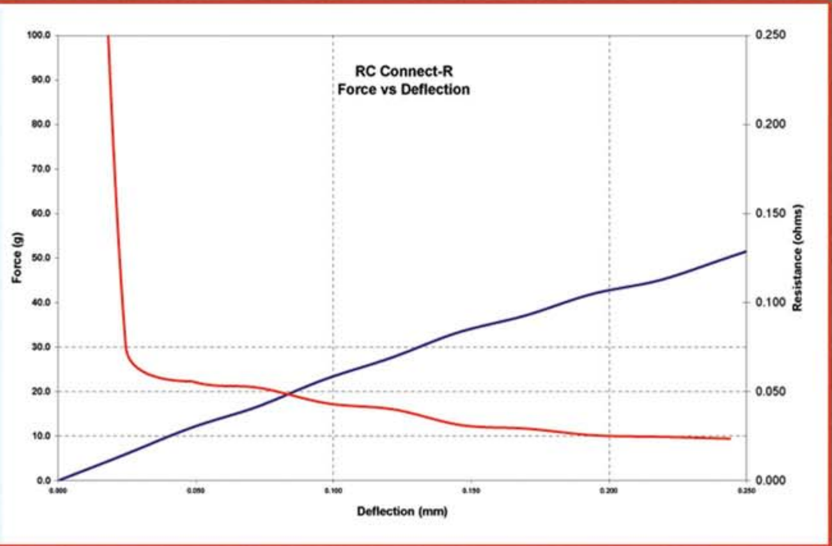
Cost & Simplicity
Revolutionary Stamped Shape
Standard Metallurgy, Materials, Plating
Designed for High Volume Automated Assembly



US Patent # 7,556,503. Other US & Foreign Patents Pending.



AC Performance at .8mm Pitch



Force vs. Deflection vs. Resistance at .8mm Pitch

The Next Generation of Stamped Contact Technology

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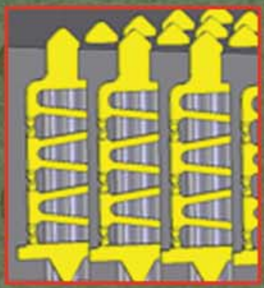
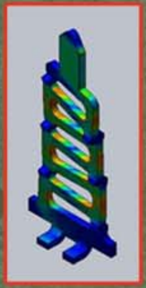
Area Array



USA Dime

Compressed



15 Degree Lateral "Scrub" Action At Tip Penetrates Oxides